

Basic information

DEA - Delegated acts procedure

[2018/2947\(DEA\)](#)

Procedure completed - delegated act enters into force

Exemption for lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

Supplementing [2008/0240\(COD\)](#)

Subject

3.40.06 Electronics, electrotechnical industries, ICT, robotics

3.70.13 Dangerous substances, toxic and radioactive wastes (storage, transport)